



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



NOTES :

1- MATERIAL:

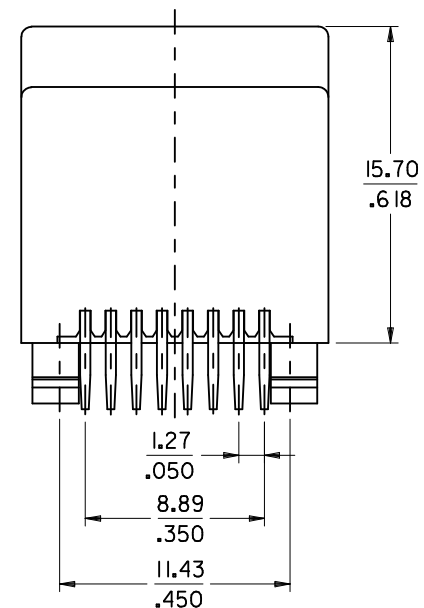
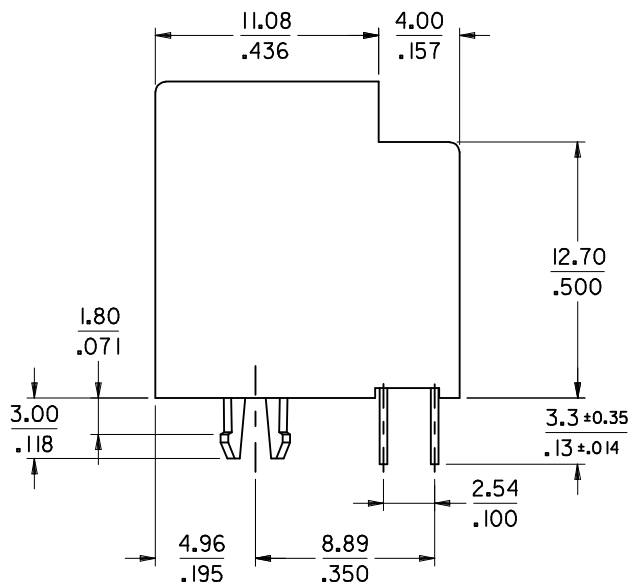
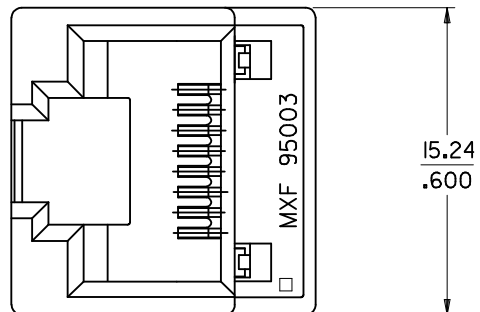
-HOUSING: POLYESTER FIBER GLASS FILLED UL 94-V0
COLOR BLACK.

-TERMINAL: PHOSPHOR BRONZE.

PLATING :

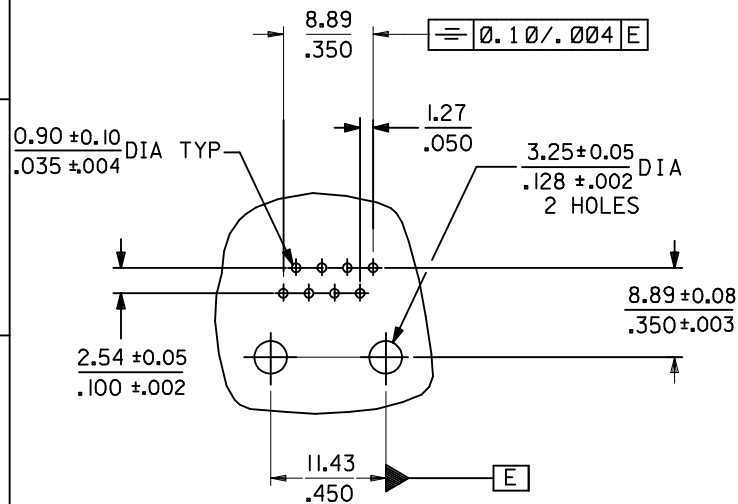
POST PLATE 0.00127-0.00152/.000050-.000060 GOLD IN
CONTACT AREA , 0.00190/.000075 MIN PURE TIN
IN TAIL AREA BOTH OVER 0.00127/.000050 MIN NICKEL
OVERALL.

- 2- JACK FOR MATING WITH F.C.C. 68 PLUGS (90075 MOLEX SERIES).
- 3- PRODUCT SPECIFICATION PS-95003 AND PS-85505 (SECTION 5.2).
- 4- APPLICATION SPECIFICATION AS-95001.
- 5- PACKAGING SPECIFICATION PK-95003 SHEET 1:
(TRAY PACKAGING).
- 6- EXCEEDS CATEGORY 5E PERFORMANCE.



P.C.B. MOUNTING PATTERN
(see from component side)

SCALE 2:1



ENTER DESCRIPTION EC NO: MGZ005-0151 DRWN: CSEBASTI 2004/10/25 CHKD: FCARBET 2004/10/25 APPR: KNOLLER 2004/11/09	QUALITY SYMBOLS ▽=0 ∇=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM/IN		SCALE 4:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		mm	INCH	DRAWN BY HB	DATE 99/08/18	TITLE HIGH SPEED MODULAR JACK TOP ENTRY LOW PROFILE THROUGH HOLE 8 CKTS			
B	REV	4 PLACES	± ---	± ---	CHECKED BY ER	DATE 99/08/18	MOLEX INCORPORATED		
		3 PLACES	± ---	± .006	APPROVED BY FB	DATE 99/08/18			
		2 PLACES	± 0.15	± .010	MATERIAL NO. 85511-0001		DOCUMENT NO. SD-85511-001	SHEET NO. 1 OF 1	
		1 PLACE	± 0.25	± ---	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				
		ANGULAR ± 1/2°		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					